

2

, , BGA, CSP

1 ,

2 ,

3 가 ,

4a 가 ,

4b ,

5 , (hole) 가 .

* *

10, 110: 11:

12: 20, 200:

30: (solder) 31, 131:

32: (bonding wire)

40a: 40b:

50: 51: (heater block)

60, 160: 60a:

60b: 63:

70a, 70b, 70c: (via hole)

80a, 180a: (solder bump) 80b: (solder ball)

81: (solder fillet) 82: (hole)

83a, 83c: 83b :

(flexible)

(solder bump)

가

| | | | |
|-----------|------------|-----------------|--------------------|
| (31) | (10) | 1 | (11,12; substrate) |
| 1), | (60a,60b), | (31) | (100) |
| e) | (31) | (11, 12) | (32; bonding wir |
| 0a) | (60b) | (70a; via hole) | (11, 12) |
| (20) | (11) | (60b) | (11, 12) |
| (70a) | (10) | (12) | (60a, 60b) |
| 80a) | (63) | (11, 12) | (60a) |
| 0a, 60b), | (60a, 60b) | (70a) | (6 |

(10)

2

3

가

가

가

가

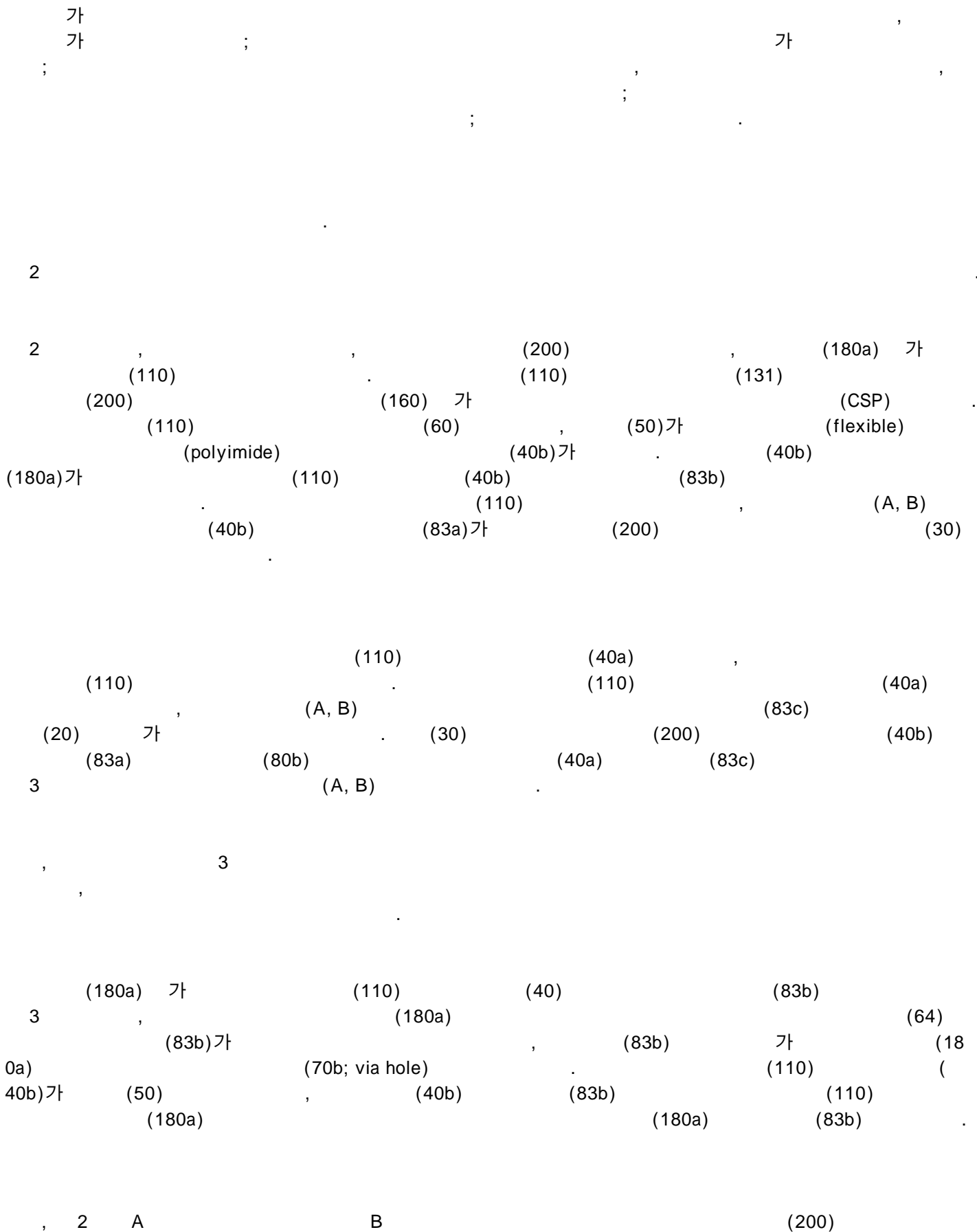
가

가

가

(CSP; chip scale package)

가



(40a, 40b) (110) (40a, 40b)
 (30) (80b) (60) (40a, 40b) (83a, 83c)
 (40a) (83c) (200) (40b) (83a)
 40b) (83a, 83c) (200) (40a, 40b) (40a,
 (64) (83a, 83c) (70c) 5
 (40a, 40b) (110) (60)
 가 (82)

(110) (40a, 40b) (83a, 83c)
 2 4a (200) (30)
 (40a, 40b) (heater block; 51) 가 (40b) (f
 lux) (80b) (40a)
 가

4b (200) (solder filet; 81) (80b)

(CSP)

(57)

1.

가 ;

가

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2.

1 ,

3.

1 , , ; , 가 , ;

4.

3 , 가 ,

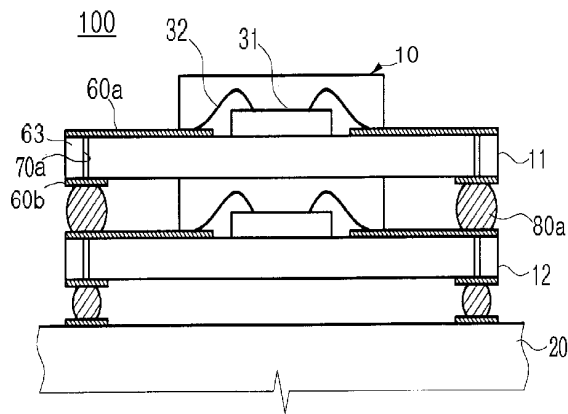
5.

3 , 가 가 , , 가

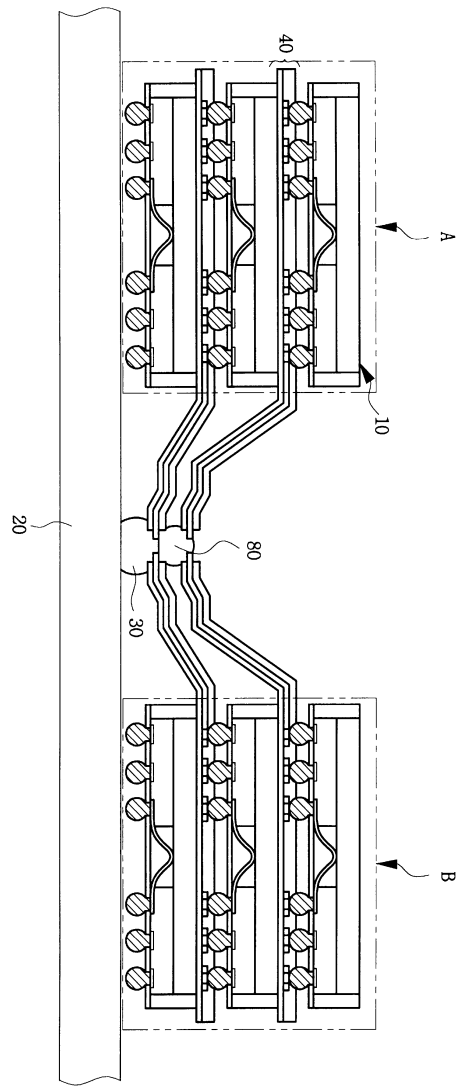
6.

3 , , .

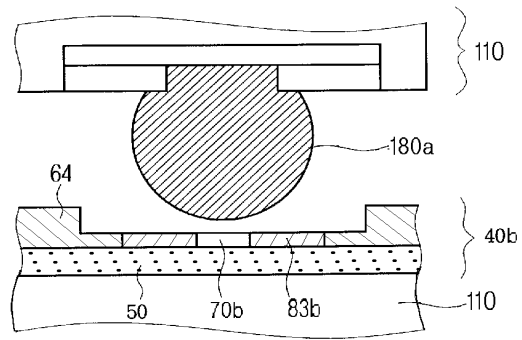
1



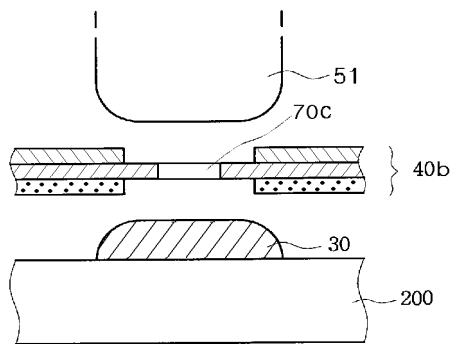
2



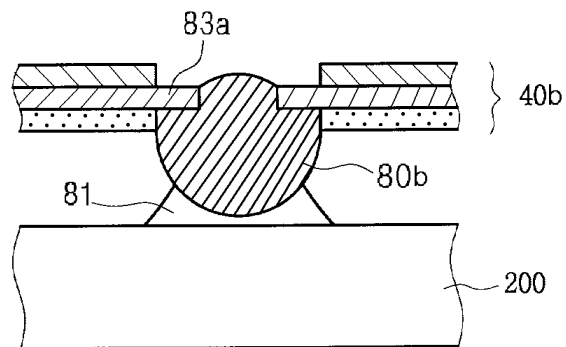
3



4a



4b



5

